504301591 03/31/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4348272

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MOTONOBU TAKEYA	03/31/2017
YOUNG HYUN KIM	03/31/2017
JONG IK LEE	03/31/2017

RECEIVING PARTY DATA

Name:	SEOUL SEMICONDUCTOR CO., LTD.	
Street Address:	97-11, SANDAN-RO 163BEON-GIL, DANWON-GU, GYEONGGI-DO	
City:	ANSAN-SI	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	15429	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15476469

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7032885105

Email: PATENT@PARK-LAW.COM
Correspondent Name: H.C. PARK & ASSOCIATES, PLC
Address Line 1: 1894 PRESTON WHITE DRIVE
Address Line 4: RESTON, VIRGINIA 20191

ATTORNEY DOCKET NUMBER:	P6811US00	
NAME OF SUBMITTER:	HAE-CHAN PARK	
SIGNATURE:	/Hae-Chan Park/	
DATE SIGNED:	ED: 03/31/2017	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 3

source=P6811US00 Executed Assignment serving as Declaration to be filed#page1.tif source=P6811US00 Executed Assignment serving as Declaration to be filed#page2.tif source=P6811US00 Executed Assignment serving as Declaration to be filed#page3.tif

PATENT 504301591 REEL: 041815 FRAME: 0458

As amended on

ASSIGNMENT SERVING AS DECLARATION PER 37 C.F.R. § 1.63(e)

As a below named inventor and Assignor, I declare that:

This assignment and declaration are directed to:

The attached application entitled DISPLAY APPATUS AND

MANUFACTURING METHOD THEREOF having attorney docket number P6811US00 ("Application"), which claims benefit of:

U.S. Provisional Application No. 62/316,927, filed April 1, 2016.

The above-identified Application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the Application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in the Application,

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Seoul Semiconductor Co., Ltd. 97-11, Sandan-ro 163beon-gil Danwon-gu, Gyeonggi-do Ansan-si 15429 Republic of Korea

Seoul Semiconductor Co., Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

(if applicable):

Docket No. P6811US00

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Inventor and Assignor has hereunto set hand and seal.

First Inventor's and Assignor's Name:	Motonobu TAKEYA
Address:	97-11, Sandan-ro 163beon-gil Danwon Gu Ansan-si Gyeonggi-do 15429 Republic of Korea
First Inventor's and Assignor's Signature:	竹谷元伸
Date:	2017. 3.3/
Second Inventor's and Assignor's Name:	Young Hyun KIM
Address:	97-11, Sandan-ro 163beon-gil, Danwon-gu Ansan-si Gyeonggi-do 15429 Republic of Korea
Second Inventor's and Assignor's Signature:	金荣现
Date:	2017, 3.31



Docket No. P6811US00

Third Inventor's and Assignor's Name: Jong Ik LEE

Address: 97-11, Sandan-ro 163beon-gil, Danwon-gu

Ansan-si, Gyeonggi-do 15429

Republic of Korea

Third Inventor's and Assignor's Signature:

Date: 2017.3.31

Page 3 of 3

PATENT REEL: 041815 FRAME: 0461

RECORDED: 03/31/2017